

Attorney Docket No. 9180-10CT

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Glenn A. Rinne et al;
Application No.: 10/790,967
Filed: March 2, 2004
For: LOW TEMPERATURE METHODS OF BONDING COMPONENTS AND
RELATED STRUCTURES

Date: February 1, 2006

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §1.97(c)

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

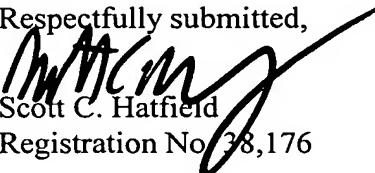
In accordance with the requirements of 37 C.F.R. § 1.97(c)(1), the following Certification as specified in 37 C.F.R. § 1.97(e) is made:

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), the Commissioner is authorized to charge the \$180.00 fee specified in 37 C.F.R. § 1.17(p) and any deficiency or credit any overpayment to Deposit Account No. 50-0220.



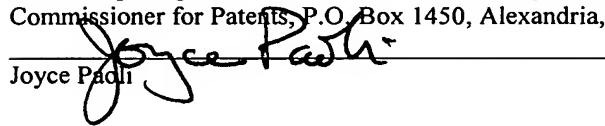
In re: Glenn A. Rinne et al;
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Page 2

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and Section 609 of the MPEP.

Respectfully submitted,

Scott C. Hatfield
Registration No. 38,176

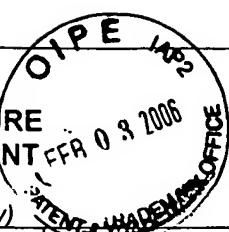
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Joyce Pauli

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(Use as many sheets as necessary)



		Complete if Known	
Application Number	10/790,967		
Filing Date	March 2, 2004		
First Named Inventor	Glenn A. Rinne		
Group Art Unit	1725		
Examiner Name	Michael Aboagye		
Attorney Docket Number	9180-10CT		

Sheet

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of

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		Number	Kind Code (if known)		
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Examiner Signature

Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<p>Substitute form 1449A/PTO</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p><i>(use as many sheets as necessary)</i></p>				<p>Complete if Known</p>	
				Application Number	10/790,967
				Filing Date	March 2, 2004
				First Named Inventor	Glenn A. Rinne
				Group Art Unit	1725
				Examiner Name	Michael Aboagye
Sheet	2	of	7	Attorney Docket Number	9180-10CT

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				Examiner Name	Michael Aboagye
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Group Art Unit	1725
Examiner Name	Michael Aboagye

Attorney Docket Number 9180-10CT

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Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T
		Office	Number	Kind Code (if known)			
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Examiner Name	Michael Aboagye				

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OTHER NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
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	237.	Arai et al. "Sn-Ag Solder Bump Formation for Flip-Chip Bonding by Electroplating" <i>Journal of the Electrochemical Society</i> 150(10): c730-c734 (2003)	
	238.	Audet, et al; <i>Low Cost Bumping Process for Flip Chip</i> , Proc. 1995 International Flip Chip, BGA, and Ado Pkg. Symposium ITAP 95, '95 Flip Chip, BGA, TAB & AP Symposium, pp 16-21 (1995).	
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	240.	Choi et al; <i>Electromigration of Flip Chip Solder Bump on Cu/Ni(V) A1 Thin Film Under Bump Metallization</i> ; <i>2002 Electronic Components and Technology Conference</i> ; pp 1201-1205.	
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Sheet	7	of	7	Attorney Docket Number	9180-10CT
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		Small Form Factor Solutions, 1999.	
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